Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

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**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .002” X .003”**

**Backside Potential: Collector**

**Mask Ref: DSL0445C**

**APPROVED BY: DK DIE SIZE .010” X .015” DATE: 10/4/21**

**MFG: MOTOROLA THICKNESS .008” P/N: 2N3546**

**DG 10.1.2**

#### Rev B, 7/19/02